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# Refine Search

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L9	0

**Database:**

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**Search:**

L10

**Refine Search****Recall Text****Clear****Interrupt**

## Search History

**DATE: Wednesday, September 22, 2004** [Printable Copy](#) [Create Case](#)**Set Name Query**  
side by side**Hit Count Set Name**  
result set*DB=TDBD; PLUR=YES; OP=OR*L10 L9 0 L10*DB=DWPI; PLUR=YES; OP=OR*L9 L8 0 L9*DB=EPAB; PLUR=YES; OP=OR*L8 L7 0 L8*DB=USOC; PLUR=YES; OP=OR*L7 L6 0 L7*DB=PGPB; PLUR=YES; OP=OR*L6 L5 0 L6*DB=USPT; PLUR=YES; OP=OR*L5 L4 and (via or "feed through") 0 L5L4 L3 and interlayer 1 L4L3 L1 same (copper near8 "etch stop") 3 L3L2 L1 same copper 4810 L2

L1 (insulat\$6 near5 substrate) 70637 L1

END OF SEARCH HISTORY

h e b b cg b e e ch